

/ Descriptions

TO-220F

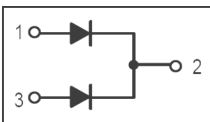
Ultrafast Recovery Diode in a TO-220F Plastic Package.

/ Features

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

/ Applications

For high frequency, high voltage, high current rectifier diode, freewheeling diode.

/ Equivalent Circuit**/ Pinning**

PIN1 Anode PIN 2 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

See Marking Instructions

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	200	V
RMS Voltage	V_{RMS}	140	V
DC Blocking Voltage	V_{DC}	200	V
Average Forward Current	I_F	2 10	A
Non Repetitive Peak Surge Current	I_{FSM}	120	A
Thermal Resistance Junction to Case	R_{JC}	3.3	/W
Operating Junction Temperature	T_J	150	
Storage Temperature Range	T_{stg}	-55 150	

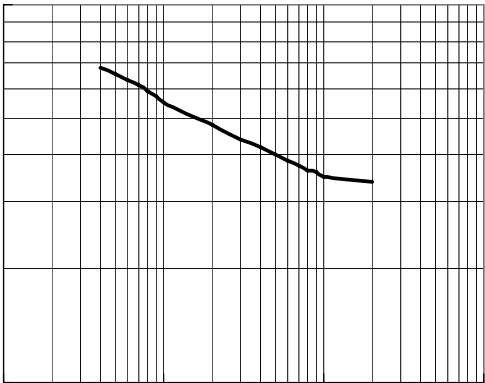
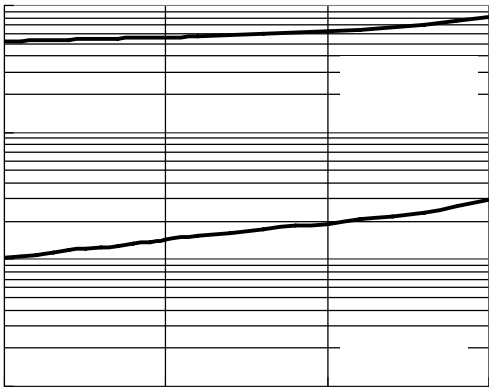
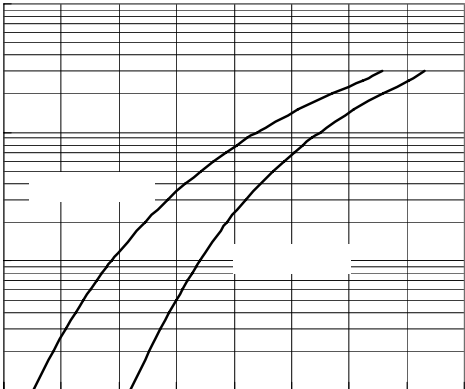
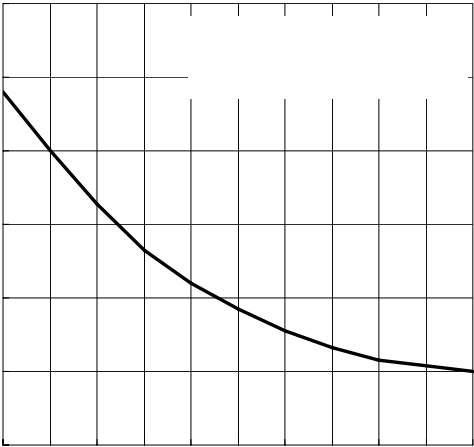
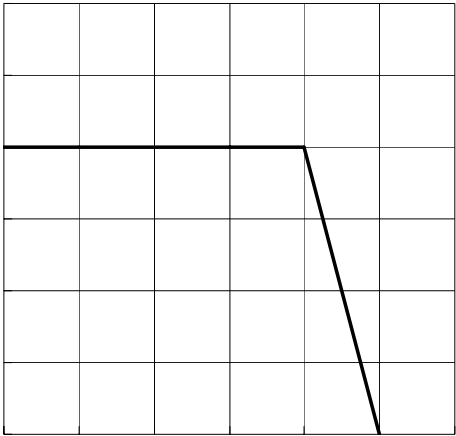
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	$I_F=2A$ $T_c=25$		0.79		V
		$I_F=2A$ $T_c=125$		0.65		V
		$I_F=10A$ $T_c=25$		0.95	1.0	V
		$I_F=10A$ $T_c=125$		0.84	0.9	V
Instantaneous Reverse Current	I_R Note 1	$V_R=200V$ $T_a=25$			10	A
		$V_R=200V$ $T_a=125$			150	A
Reverse Recovery Time	t_{rr}	$I_R=1.0A$ $I_{RR}=0.25A$ $I_F=0.5A$			35	ns

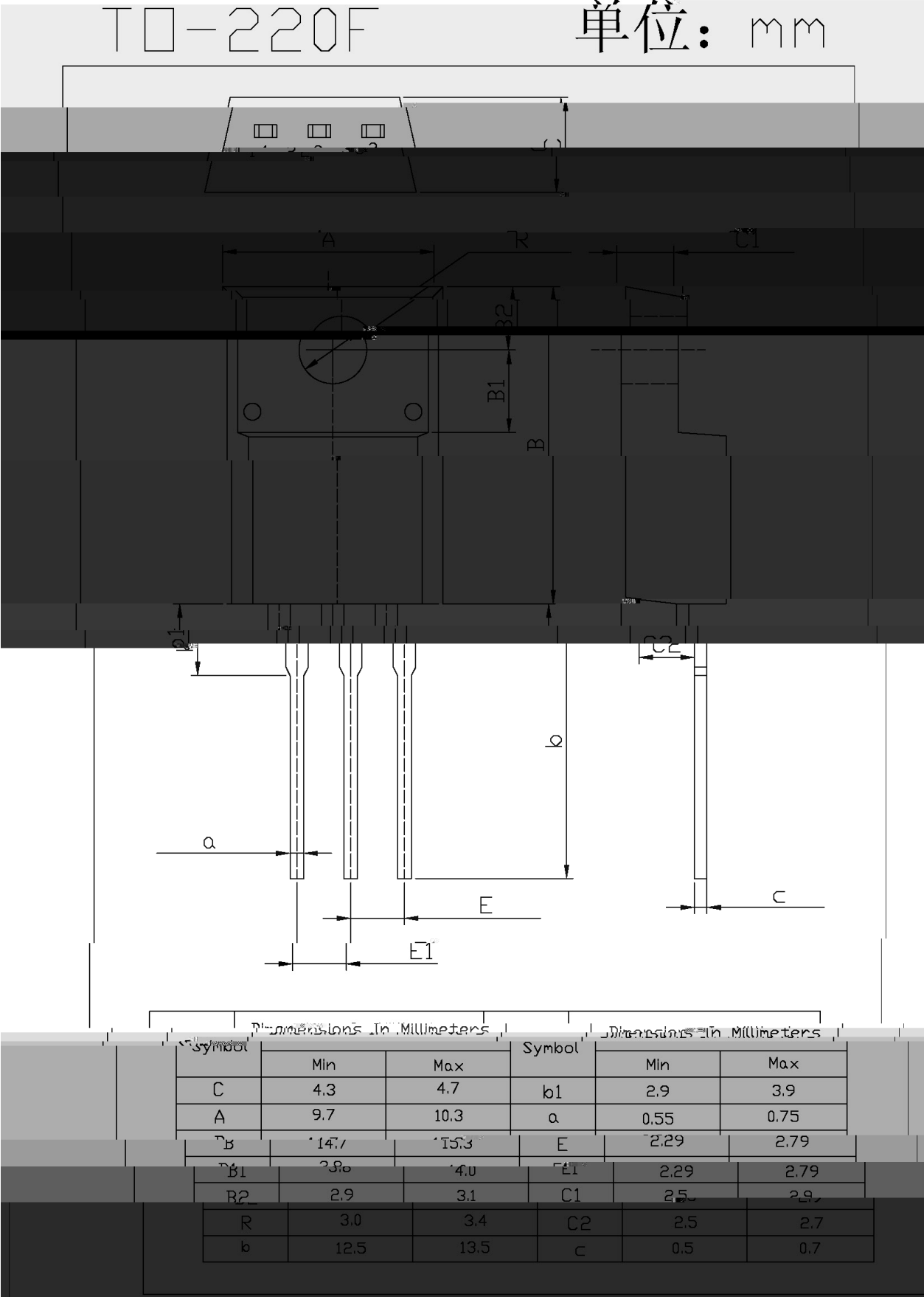
/Notes

1. /Short duration pulse test used to minimize self-heating effect.
2. / Unless otherwise noted, values for the parameters of a single chip

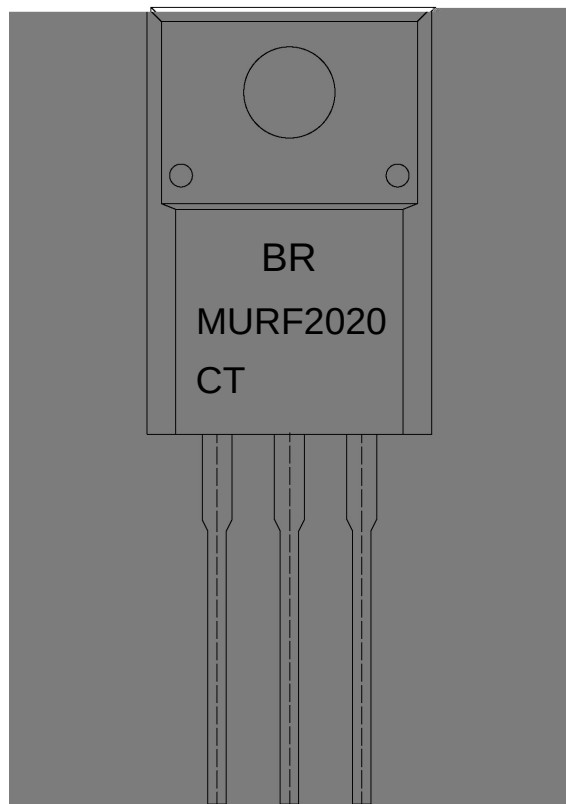
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



BR

MURF2020

CT:

Note:

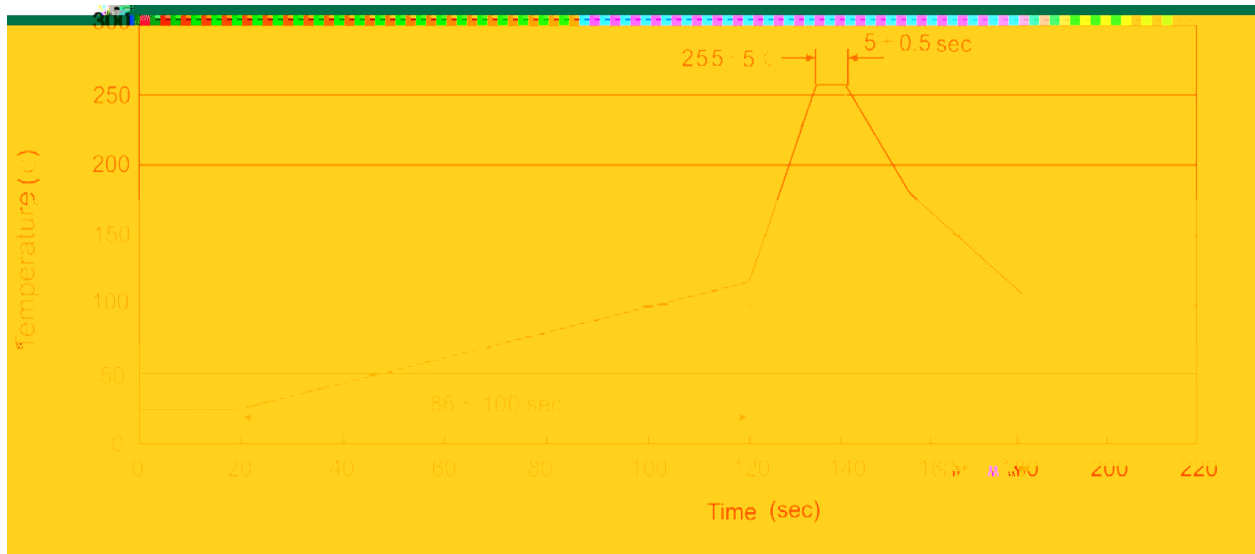
BR: Company Code

MURF2020: Product Type.

CT: Internal Structure

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只袋	袋盒	只盒	盒箱	只箱	袋	盒	箱

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只套管	套管盒	只盒	盒箱	只箱	套管	盒	箱

/ Notices